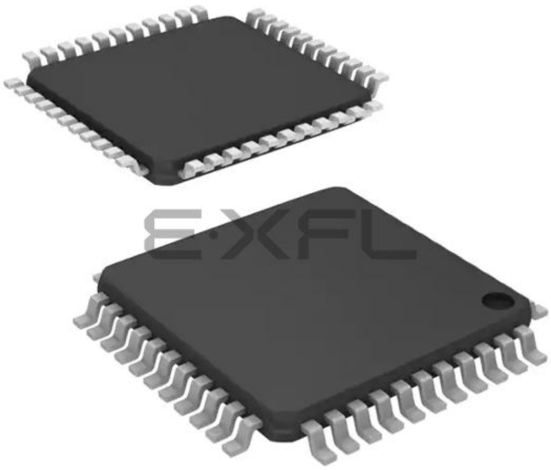

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

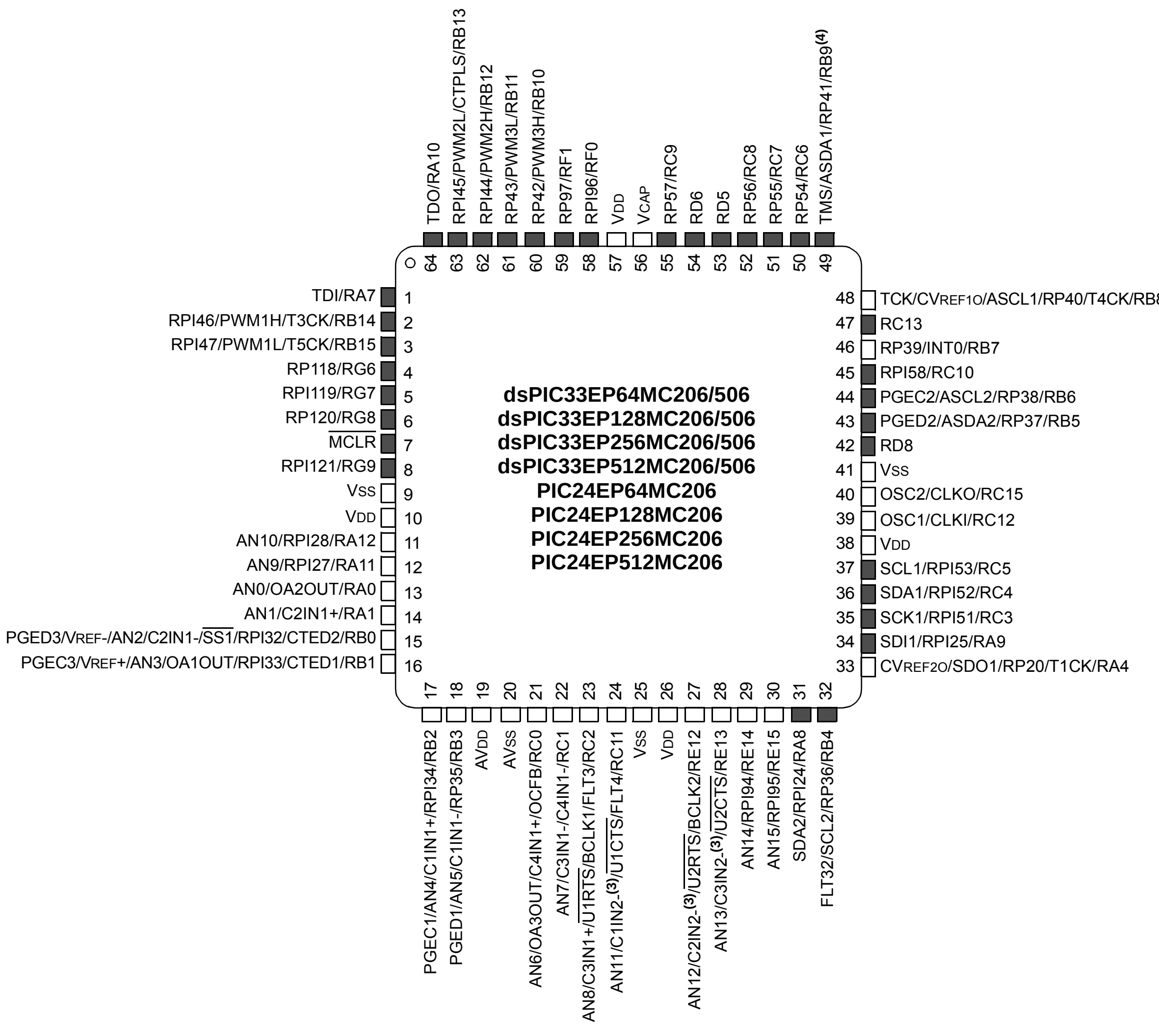
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256gp204t-i-pt

Pin Diagrams (Continued)

64-Pin TQFP[1,2,3]

■ = Pins are up to 5V tolerant



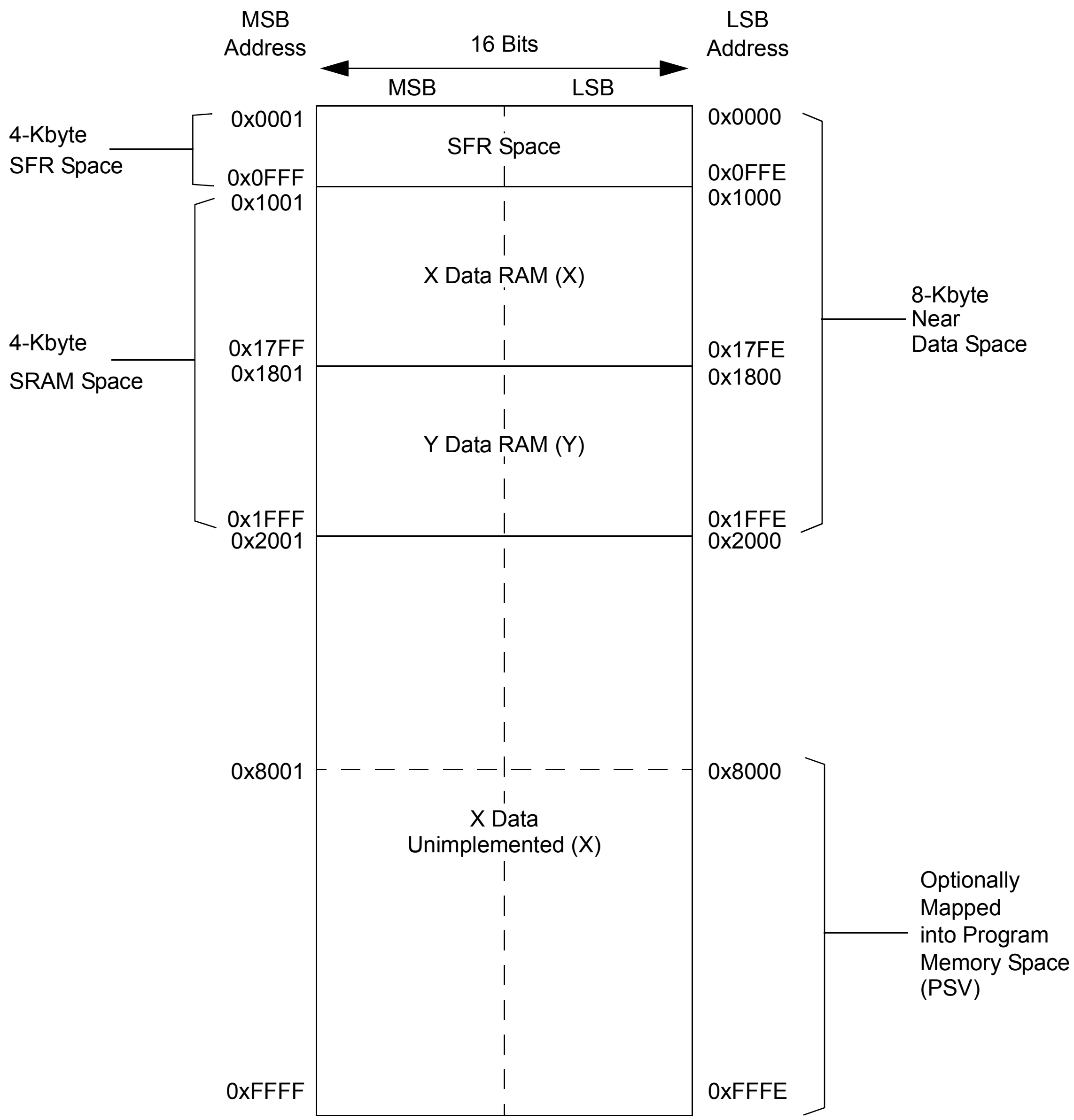
Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 4-7: DATA MEMORY MAP FOR dsPIC33EP32MC20X/50X AND dsPIC33EP32GP50X DEVICES



Note: Memory areas are not shown to scale.

4.4.3 DATA MEMORY ARBITRATION AND BUS MASTER PRIORITY

EDS accesses from bus masters in the system are arbitrated.

The arbiter for data memory (including EDS) arbitrates between the CPU, the DMA and the ICD module. In the event of coincidental access to a bus by the bus masters, the arbiter determines which bus master access has the highest priority. The other bus masters are suspended and processed after the access of the bus by the bus master with the highest priority.

By default, the CPU is Bus Master 0 (M0) with the highest priority and the ICD is Bus Master 4 (M4) with the lowest priority. The remaining bus master (DMA Controller) is allocated to M3 (M1 and M2 are reserved and cannot be used). The user application may raise or lower the priority of the DMA Controller to be above that of the CPU by setting the appropriate bits in the EDS Bus Master Priority Control (MSTRPR) register. All bus masters with raised priorities will maintain the same priority relationship relative to each other (i.e., M1 being highest and M3 being lowest, with M2 in between). Also, all the bus masters with priorities below that of the CPU maintain the same priority relationship relative to each other. The priority schemes for bus masters with different MSTRPR values are tabulated in Table 4-62.

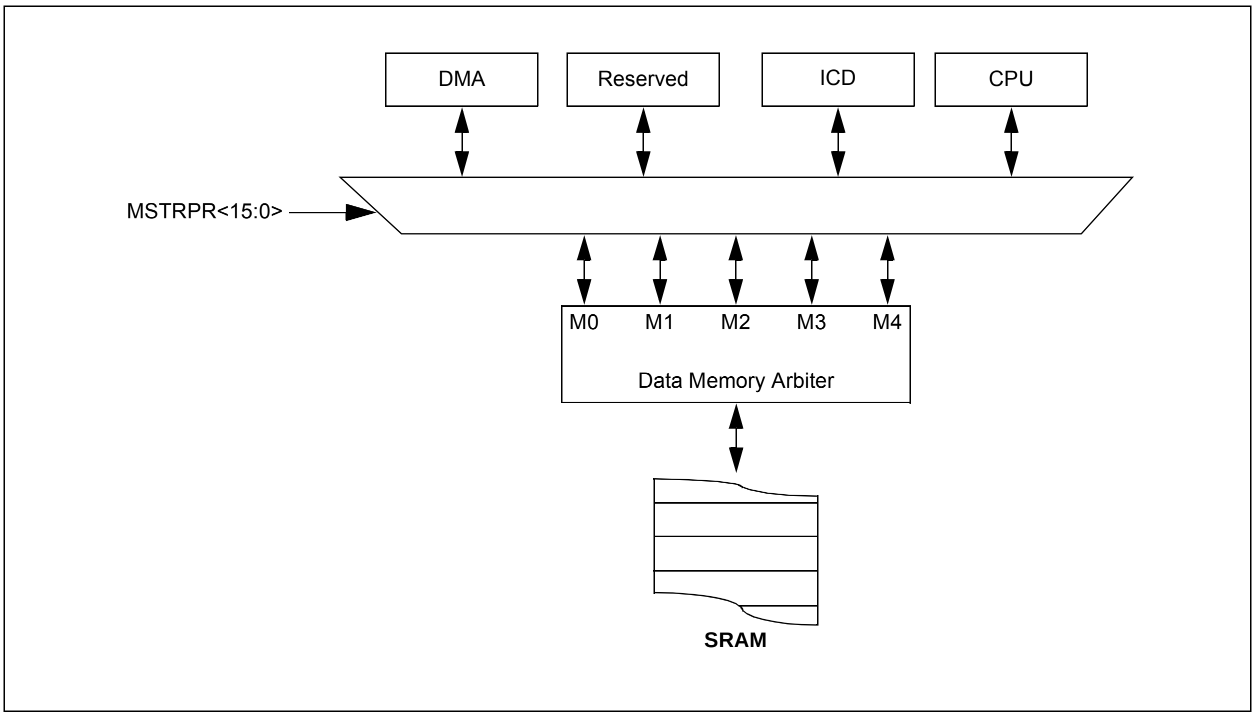
This bus master priority control allows the user application to manipulate the real-time response of the system, either statically during initialization or dynamically in response to real-time events.

TABLE 4-62: DATA MEMORY BUS ARBITER PRIORITY

Priority	MSTRPR<15:0> Bit Setting(1)	
	0x0000	0x0020
M0 (highest)	CPU	DMA
M1	Reserved	CPU
M2	Reserved	Reserved
M3	DMA	Reserved
M4 (lowest)	ICD	ICD

Note 1: All other values of MSTRPR<15:0> are reserved.

FIGURE 4-18: ARBITER ARCHITECTURE



REGISTER 8-11: DMAPWC: DMA PERIPHERAL WRITE COLLISION STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **PWCOL3:** DMA Channel 3 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

bit 2 **PWCOL2:** DMA Channel 2 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

bit 1 **PWCOL1:** DMA Channel 1 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

bit 0 **PWCOL0:** DMA Channel 0 Peripheral Write Collision Flag bit
1 = Write collision is detected
0 = No write collision is detected

NOTES:

NOTES:

11.5 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 30-11, under “Injection Current”, have internal protection diodes to V_{DD} and V_{SS}. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins, with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the V_{SS} and V_{DD} supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the V_{DD} and V_{SS} power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note: Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(V_{DD} – 0.8), not V_{DD}. This value is still above the minimum V_{IH} of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the V_{OH}/I_{OH} and V_{OL}/I_{OL} DC characteristic specification. The respective I_{OH} and I_{OL} current rating only applies to maintaining the corresponding output at or above the V_{OH}, and at or below the V_{OL} levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum V_{IH}/V_{IL} levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

   V_{OH} = 2.4V @ I_{OH} = -8 mA and V_{DD} = 3.3V

   The maximum output current sourced by any 8 mA I/O pin = 12 mA.

   LED source current < 12 mA is technically permitted. Refer to the V_{OH}/I_{OH} graphs in **Section 30.0 “Electrical Characteristics”** for additional information.
6. The Peripheral Pin Select (PPS) pin mapping rules are as follows:
   a) Only one “output” function can be active on a given pin at any time, regardless if it is a dedicated or remappable function (one pin, one output).
   b) It is possible to assign a “remappable output” function to multiple pins and externally short or tie them together for increased current drive.
   c) If any “dedicated output” function is enabled on a pin, it will take precedence over any remappable “output” function.
   d) If any “dedicated digital” (input or output) function is enabled on a pin, any number of “input” remappable functions can be mapped to the same pin.
   e) If any “dedicated analog” function(s) are enabled on a given pin, “digital input(s)” of any kind will all be disabled, although a single “digital output”, at the user’s cautionary discretion, can be enabled and active as long as there is no signal contention with an external analog input signal. For example, it is possible for the ADC to convert the digital output logic level, or to toggle a digital output on a comparator or ADC input provided there is no external analog input, such as for a built-in self-test.
   f) Any number of “input” remappable functions can be mapped to the same pin(s) at the same time, including to any pin with a single output from either a dedicated or remappable “output”.

REGISTER 11-10: RPINR18: PERIPHERAL PIN SELECT INPUT REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	U1RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **U1RXR<6:0>:** Assign UART1 Receive (U1RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

REGISTER 11-11: RPINR19: PERIPHERAL PIN SELECT INPUT REGISTER 19

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	U2RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **U2RXR<6:0>:** Assign UART2 Receive (U2RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

REGISTER 15-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Trigger/Synchronization Source Selection bits

`11111` = OCxRS compare event is used for synchronization
`11110` = INT2 pin synchronizes or triggers OCx
`11101` = INT1 pin synchronizes or triggers OCx
`11100` = CTMU module synchronizes or triggers OCx
`11011` = ADC1 module synchronizes or triggers OCx
`11010` = CMP3 module synchronizes or triggers OCx
`11001` = CMP2 module synchronizes or triggers OCx
`11000` = CMP1 module synchronizes or triggers OCx
`10111` = Reserved
`10110` = Reserved
`10101` = Reserved
`10100` = Reserved
`10011` = IC4 input capture event synchronizes or triggers OCx
`10010` = IC3 input capture event synchronizes or triggers OCx
`10001` = IC2 input capture event synchronizes or triggers OCx
`10000` = IC1 input capture event synchronizes or triggers OCx
`01111` = Timer5 synchronizes or triggers OCx
`01110` = Timer4 synchronizes or triggers OCx
`01101` = Timer3 synchronizes or triggers OCx
`01100` = Timer2 synchronizes or triggers OCx **(default)**
`01011` = Timer1 synchronizes or triggers OCx
`01010` = PTGOx synchronizes or triggers OCx[3]
`01001` = Reserved
`01000` = Reserved
`00111` = Reserved
`00110` = Reserved
`00101` = Reserved
`00100` = OC4 module synchronizes or triggers OCx[1,2]
`00011` = OC3 module synchronizes or triggers OCx[1,2]
`00010` = OC2 module synchronizes or triggers OCx[1,2]
`00001` = OC1 module synchronizes or triggers OCx[1,2]
`00000` = No Sync or Trigger source for OCx

Note 1: Do not use the OCx module as its own Synchronization or Trigger source.

2: When the OCy module is turned OFF, it sends a trigger out signal. If the OCx module uses the OCy module as a Trigger source, the OCy module must be unselected as a Trigger source prior to disabling it.

3: Each Output Compare x module (OCx) has one PTG Trigger/Synchronization source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO0 = OC1
PTGO1 = OC2
PTGO2 = OC3
PTGO3 = OC4

16.0 HIGH-SPEED PWM MODULE (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"High-Speed PWM"** (DS70645) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices support a dedicated Pulse-Width Modulation (PWM) module with up to 6 outputs.

The high-speed PWMx module consists of the following major features:

- Three PWM generators
- Two PWM outputs per PWM generator
- Individual period and duty cycle for each PWM pair
- Duty cycle, dead time, phase shift and frequency resolution of TCY/2 (7.14 ns at FCY = 70MHz)
- Independent Fault and current-limit inputs for six PWM outputs
- Redundant output
- Center-Aligned PWM mode
- Output override control
- Chop mode (also known as Gated mode)
- Special Event Trigger
- Prescaler for input clock
- PWMxL and PWMxH output pin swapping
- Independent PWM frequency, duty cycle and phase-shift changes for each PWM generator
- Dead-time compensation
- Enhanced Leading-Edge Blanking (LEB) functionality
- Frequency resolution enhancement
- PWM capture functionality

> **Note:** In Edge-Aligned PWM mode, the duty cycle, dead time, phase shift and frequency resolution are 8.32 ns.

The high-speed PWMx module contains up to three PWM generators. Each PWM generator provides two PWM outputs: PWMxH and PWMxL. The master time base generator provides a synchronous signal as a common time base to synchronize the various PWM outputs. The individual PWM outputs are available on the output pins of the device. The input Fault signals and current-limit signals, when enabled, can monitor and protect the system by placing the PWM outputs into a known "safe" state.

Each PWMx can generate a trigger to the ADC module to sample the analog signal at a specific instance during the PWM period. In addition, the high-speed PWMx module also generates a Special Event Trigger to the ADC module based on either of the two master time bases.

The high-speed PWMx module can synchronize itself with an external signal or can act as a synchronizing source to any external device. The SYNCI1 input pin that utilizes PPS, can synchronize the high-speed PWMx module with an external signal. The SYNCO1 pin is an output pin that provides a synchronous signal to an external device.

Figure 16-1 illustrates an architectural overview of the high-speed PWMx module and its interconnection with the CPU and other peripherals.

16.1 PWM Faults

The PWMx module incorporates multiple external Fault inputs to include FLT1 and FLT2 which are remappable using the PPS feature, FLT3 and FLT4 which are available only on the larger 44-pin and 64-pin packages, and FLT32 which has been implemented with Class B safety features, and is available on a fixed pin on all dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

These Faults provide a safe and reliable way to safely shut down the PWM outputs when the Fault input is asserted.

16.1.1 PWM FAULTS AT RESET

During any Reset event, the PWMx module maintains ownership of the Class B Fault, FLT32. At Reset, this Fault is enabled in Latched mode to ensure the fail-safe power-up of the application. The application software must clear the PWM Fault before enabling the high-speed motor control PWMx module. To clear the Fault condition, the FLT32 pin must first be pulled low externally or the internal pull-down resistor in the CNPDx register can be enabled.

> **Note:** The Fault mode may be changed using the FLTMOD<1:0> bits (FCLCON<1:0>), regardless of the state of FLT32.

REGISTER 16-14: TRIGx: PWMx PRIMARY TRIGGER COMPARE VALUE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **TRGCMP<15:0>:** Trigger Control Value bits

When the primary PWMx functions in local time base, this register contains the compare values that can trigger the ADC module.

19.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Inter-Integrated Circuit™ (I^2C™)"** (DS70330) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

3: There are minimum bit rates of approximately FCY/512. As a result, high processor speeds may not support 100 Kbit/second operation. See timing specifications, IM10 and IM11, and the **"Baud Rate Generator"** in the "*dsPIC33/PIC24 Family Reference Manual*".

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family of devices contains two Inter-Integrated Circuit (I^2C) modules: I2C1 and I2C2.

The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The I^2C module has a 2-pin interface:

- The SCLx pin is clock
- The SDAx pin is data

The I^2C module offers the following key features:

- I^2C interface supporting both Master and Slave modes of operation
- I^2C Slave mode supports 7 and 10-bit addressing
- I^2C Master mode supports 7 and 10-bit addressing
- I^2C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation, detects bus collision and arbitrates accordingly
- Intelligent Platform Management Interface (IPMI) support
- System Management Bus (SMBus) support

REGISTER 21-13: CxBUFPNT2: ECANx FILTER 4-7 BUFFER POINTER REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F7BP<3:0>				F6BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F5BP<3:0>				F4BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F7BP<3:0>:** RX Buffer Mask for Filter 7 bits
`1111` = Filter hits received in RX FIFO buffer
`1110` = Filter hits received in RX Buffer 14
•
•
•
`0001` = Filter hits received in RX Buffer 1
`0000` = Filter hits received in RX Buffer 0

bit 11-8 **F6BP<3:0>:** RX Buffer Mask for Filter 6 bits (same values as bits<15:12>)

bit 7-4 **F5BP<3:0>:** RX Buffer Mask for Filter 5 bits (same values as bits<15:12>)

bit 3-0 **F4BP<3:0>:** RX Buffer Mask for Filter 4 bits (same values as bits<15:12>)

REGISTER 21-14: CxBUFPNT3: ECANx FILTER 8-11 BUFFER POINTER REGISTER 3

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11BP<3:0>				F10BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F9BP<3:0>				F8BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F11BP<3:0>:** RX Buffer Mask for Filter 11 bits
`1111` = Filter hits received in RX FIFO buffer
`1110` = Filter hits received in RX Buffer 14
•
•
•
`0001` = Filter hits received in RX Buffer 1
`0000` = Filter hits received in RX Buffer 0

bit 11-8 **F10BP<3:0>:** RX Buffer Mask for Filter 10 bits (same values as bits<15:12>)

bit 7-4 **F9BP<3:0>:** RX Buffer Mask for Filter 9 bits (same values as bits<15:12>)

bit 3-0 **F8BP<3:0>:** RX Buffer Mask for Filter 8 bits (same values as bits<15:12>)

REGISTER 23-1: AD1CON1: ADC1 CONTROL REGISTER 1 (CONTINUED)

bit 7-5 **SSRC<2:0>:** Sample Trigger Source Select bits

If SSRCG = 1:
111 = Reserved
110 = PTGO15 primary trigger compare ends sampling and starts conversion(1)
101 = PTGO14 primary trigger compare ends sampling and starts conversion(1)
100 = PTGO13 primary trigger compare ends sampling and starts conversion(1)
011 = PTGO12 primary trigger compare ends sampling and starts conversion(1)
010 = PWM Generator 3 primary trigger compare ends sampling and starts conversion(2)
001 = PWM Generator 2 primary trigger compare ends sampling and starts conversion(2)
000 = PWM Generator 1 primary trigger compare ends sampling and starts conversion(2)

If SSRCG = 0:
111 = Internal counter ends sampling and starts conversion (auto-convert)
110 = CTMU ends sampling and starts conversion
101 = Reserved
100 = Timer5 compare ends sampling and starts conversion
011 = PWM primary Special Event Trigger ends sampling and starts conversion(2)
010 = Timer3 compare ends sampling and starts conversion
001 = Active transition on the INT0 pin ends sampling and starts conversion
000 = Clearing the Sample bit (SAMP) ends sampling and starts conversion (Manual mode)

bit 4 **SSRCG:** Sample Trigger Source Group bit

See SSRC<2:0> for details.

bit 3 **SIMSAM:** Simultaneous Sample Select bit (only applicable when CHPS<1:0> = 01 or 1x)

In 12-bit mode (AD21B = 1), SIMSAM is Unimplemented and is Read as '0':
1 = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = 1x); or samples CH0 and CH1 simultaneously (when CHPS<1:0> = 01)
0 = Samples multiple channels individually in sequence

bit 2 **ASAM:** ADC1 Sample Auto-Start bit

1 = Sampling begins immediately after the last conversion; SAMP bit is auto-set
0 = Sampling begins when the SAMP bit is set

bit 1 **SAMP:** ADC1 Sample Enable bit

1 = ADC Sample-and-Hold amplifiers are sampling
0 = ADC Sample-and-Hold amplifiers are holding
If ASAM = 0, software can write '1' to begin sampling. Automatically set by hardware if ASAM = 1. If SSRC<2:0> = 000, software can write '0' to end sampling and start conversion. If SSRC<2:0> ≠ 000, automatically cleared by hardware to end sampling and start conversion.

bit 0 **DONE:** ADC1 Conversion Status bit(3)

1 = ADC conversion cycle has completed
0 = ADC conversion has not started or is in progress
Automatically set by hardware when the ADC conversion is complete. Software can write '0' to clear the DONE status bit (software is not allowed to write '1'). Clearing this bit does NOT affect any operation in progress. Automatically cleared by hardware at the start of a new conversion.

Note 1: See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for information on this selection.
2: This setting is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
3: Do not clear the DONE bit in software if Auto-Sample is enabled (ASAM = 1).

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

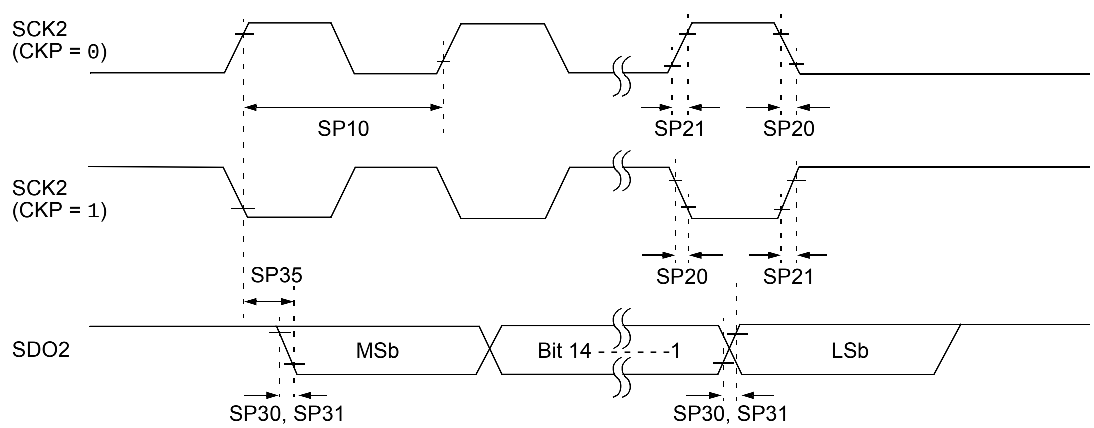
DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
Power-Down Current (IPD)(1) – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	200	μA	+85°C	
DC60c	250	500	μA	+125°C	
Power-Down Current (IPD)(1) – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X					
DC60d	25	100	μA	-40°C	3.3V
DC60a	30	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	350	800	μA	+125°C	
Power-Down Current (IPD)(1) – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	550	1000	μA	+125°C	
Power-Down Current (IPD)(1) – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X					
DC60d	35	100	μA	-40°C	3.3V
DC60a	40	100	μA	+25°C	
DC60b	250	450	μA	+85°C	
DC60c	1000	1200	μA	+125°C	
Power-Down Current (IPD)(1) – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X					
DC60d	40	100	μA	-40°C	3.3V
DC60a	45	100	μA	+25°C	
DC60b	350	800	μA	+85°C	
DC60c	1100	1500	μA	+125°C	

Note 1: IPD (Sleep) current is measured as follows:
- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = `0` (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = `0` (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

TABLE 30-33: SPI2 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 30-34	—	1	0,1	1
9 MHz	—	Table 30-35	—	0	0,1	1
15 MHz	—	—	Table 30-36	1	0	0
11 MHz	—	—	Table 30-37	1	1	0
15 MHz	—	—	Table 30-38	0	1	0
11 MHz	—	—	Table 30-39	0	0	0

FIGURE 30-14: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS

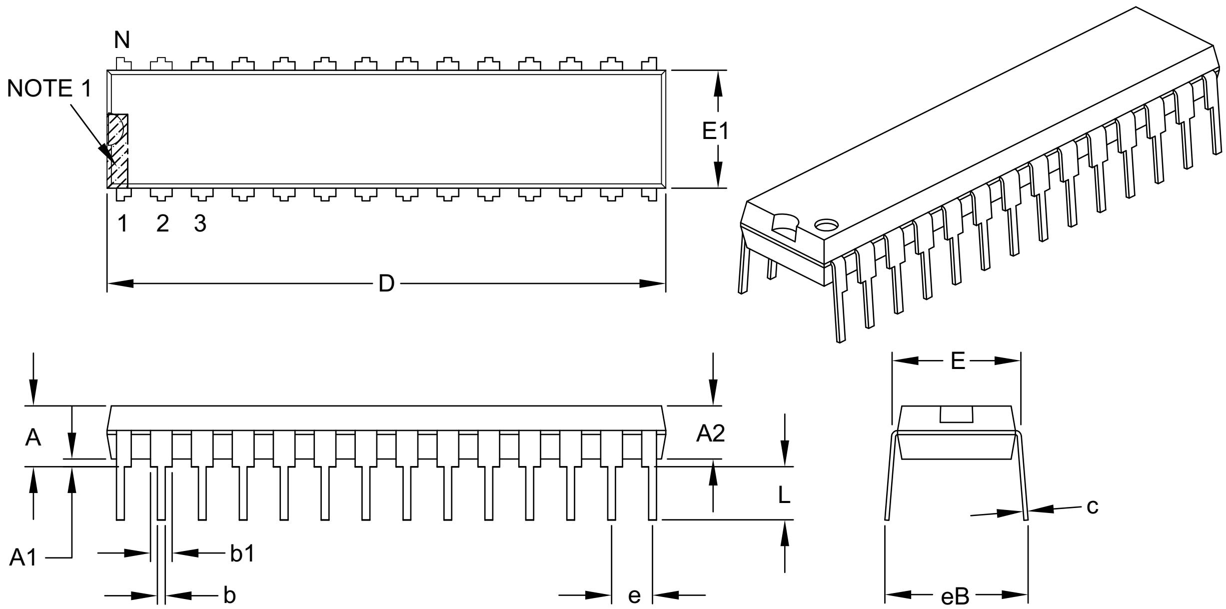


Note: Refer to Figure 30-1 for load conditions.

33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



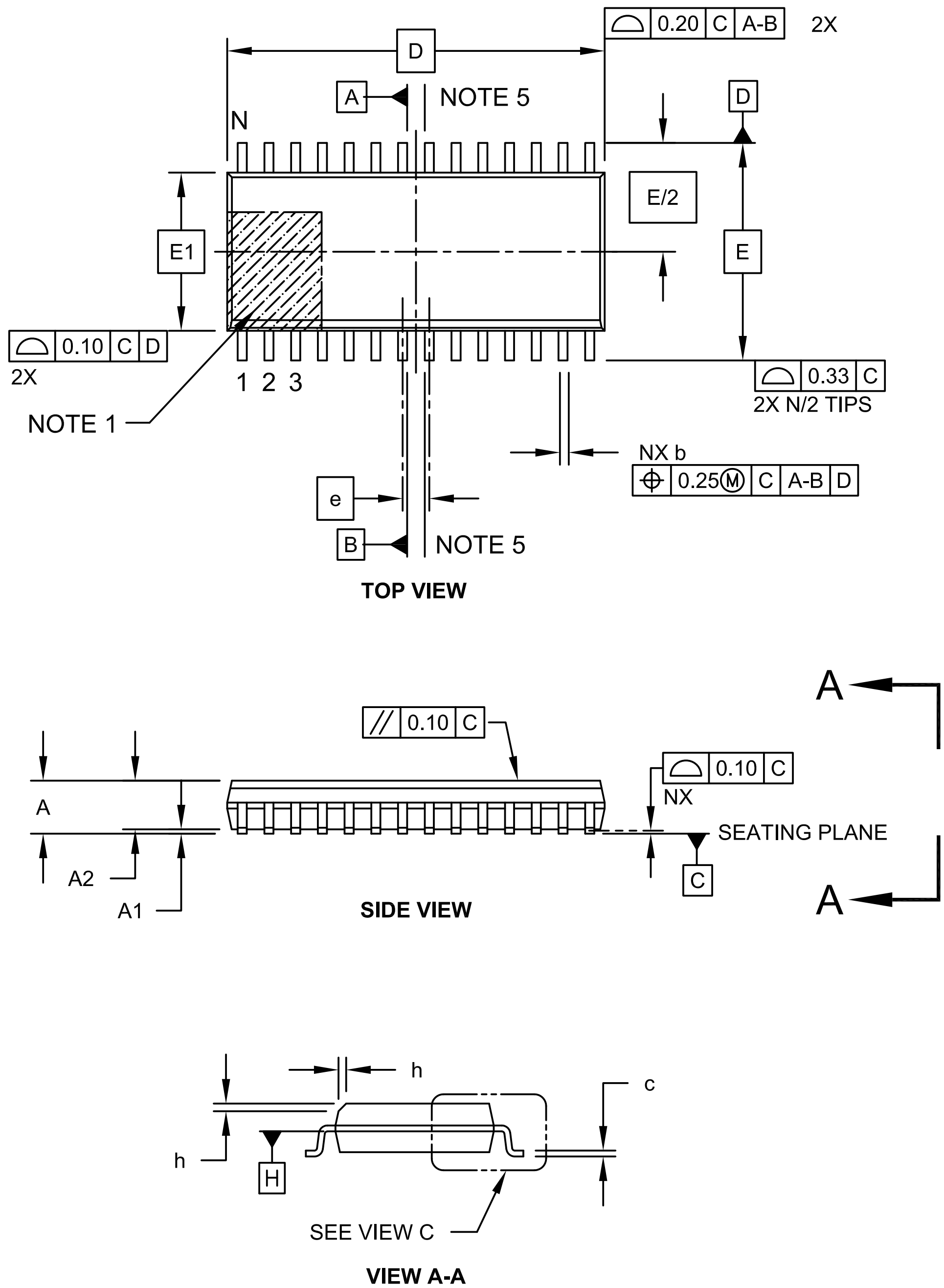
Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

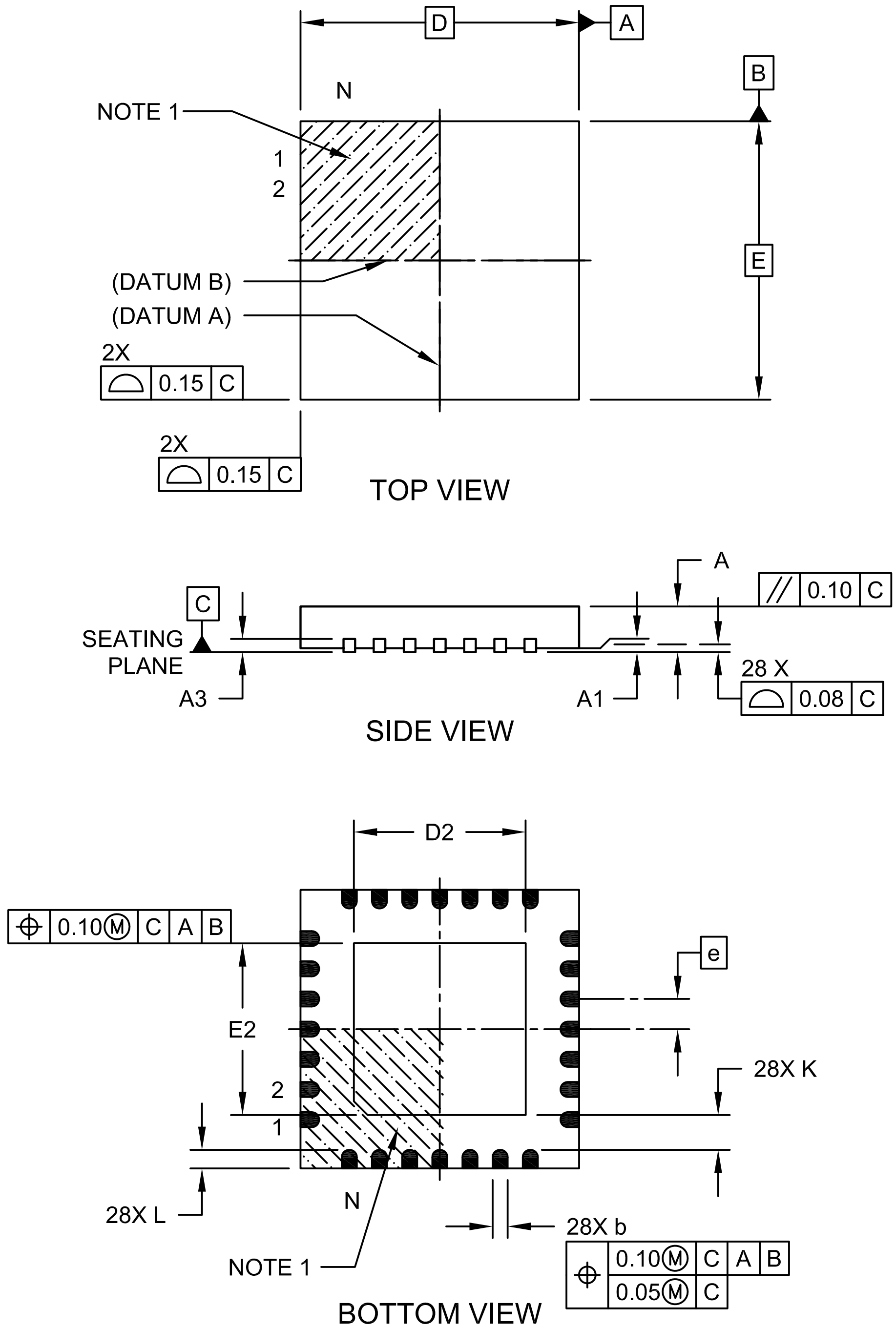
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-052C Sheet 1 of 2

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S] With 0.40 mm Terminal Length

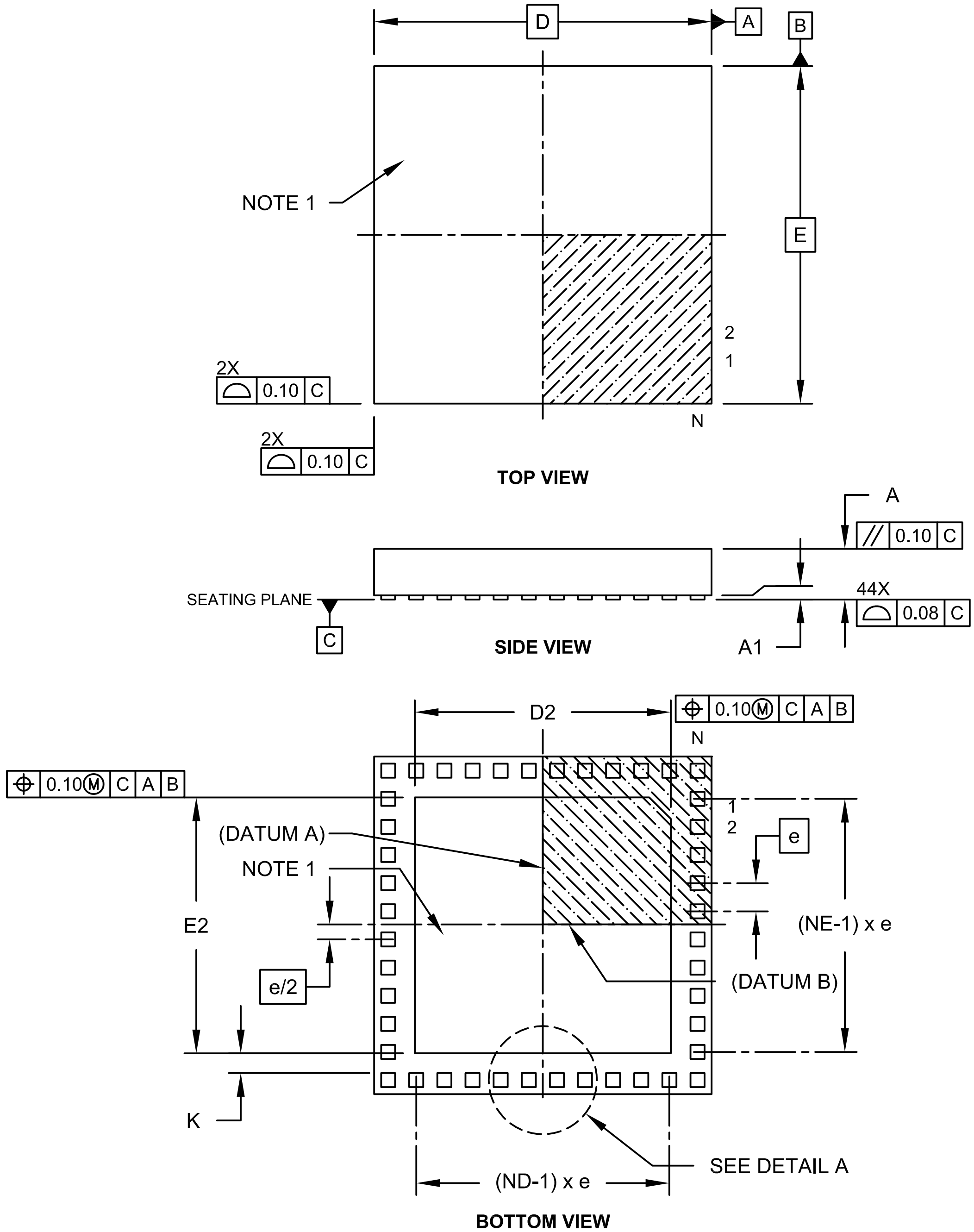
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-124C Sheet 1 of 2

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-157C Sheet 1 of 2